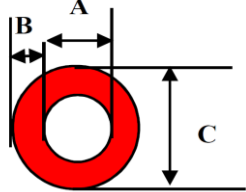


NC Drilling						
Layer Count	Minimum size(A)	Normal sizePAD(C)	Single side hole ring(B)	Minimum size PAD		
Double side	0.10mm	0.35mm	0.125mm	0.30mm		
1L+1L	0.15mm	0.40mm	0.125mm	0.35mm		
3L or more	0.15mm	0.45mm	0.15mm	0.4mm		
4L or more	0.2mm	0.5mm	0.15mm	0.45mm		
Flex-rigid	0.2mm	0.5mm	0.15mm	0.45mm		
Drilling size range			0.1mm~6.5mm			
Hole tolerance			±0.01mm			
True position size			±0.05mm			
Copper Plating						
Type	Copper weight range	Normal Capability		Special Capability	Remark	
Sculptural	Copper Plating	300±100u"		400±120u"		
Double side				450±150u"		
1L+1L				800±250u"		
3L or more		600±200u"				
4L or more						
Flex-rigid		600u" or more				
Remark	Drilling Minimum siz 0.1mm · Aspect ratio8 : 1					
Etching						
Trace width / space	Layer Count	Copper Weight	Minimum trace width	Minimum trace space	Remark	
	Singel side	1OZ	3mil	3mil	Normal Copper Plating 300±100u"	
		1/2OZ	2mil	2mil		
		1/3OZ	1.8mil	1.8mil		
	Double side	1OZ	3mil	3mil		
		1/2OZ	2.5mil	2.5mil		
		1/3OZ	2mil	2mil		
		1/3OZ	1.8mil	1.8mil		
Only PTH Cu						
Coverlay/Stiffener						
Stiffener	Material type	Tolerance	Special tolerance	Remark		
	CVL	±0.3mm	±0.2mm	CVL Spilled glue≤0.10mm Minimum SUS size3mm X 5mm		
	PI,FR4					
	SUS					
Adhesive						
Coverlay	Material type	Minimum Opening	Minimum space from Opening to inner pattern			
	CVL	0.5mm	0.30mm			
Printing						
Printing	Project	Project	Normal	Minimum	Remark	
	Silkscreen	Tolerance	±0.3mm	±0.2mm	The color is specified by the customer	
		Minimum	0.12mm	0.1mm		
		Height	1.0mm	0.8mm		
	Solder Mask Hot bake	Tolerance	±0.35mm	±0.3mm		
		Thickness	20±10um			
	Solder Mask development	Deviation	±0.075mm	±0.05mm		
		Mask spacing	0.1mm(min)			
		Minimum Opening	0.4mm X 0.4mm			
		Thickness	20±10um			
Punching						
Project	Project	Normal Tolerance	Minimum Tolerance	Remark		
Etching	Pitch to Pitch	±0.3mm	±0.2mm	The smallest tolerances require precision molding		
	Total Pitch(≤50mm)	±0.3mm	±0.2mm			
Punching	First Gold Finger Pin to Dimensions	±0.01mm	±0.05mm			
	Gold Finger to Dimensions	±0.075mm	±0.05mm			
	Dimensions	0.1mm				
	Minimum Angle R	0.2mm	0.15mm			
	NPTH to NPTH	±0.075mm	±0.05mm			
	NPTH to Dimensions	1.5mm	1.0mm			
	Trace to Dimensions	0.2mm				
	Minimum Punching hole	0.5mm				
	NPTH Tolerance	±0.5mm				
Surface Treament						
Project	Project	Ni/Au	spec	Characteristic		
Hard gold plating	Normal	Ni	2um~6um			
		Au	0.025~0.075um or 0.05um(min)			
	Thick Gold	Au	0.2um~0.8um			
Immersion gold	Normal	Ni	0.75um~2um			
		Au	0.025~0.075um			
OSP	thickness	OSP	0.2um~0.5um			
Thickness						
Board thickness tolerance	1L、2L	±0.03mm(±10%)				
	3L or more	±0.05mm(±10%)				